

Method and apparatus for dispensing solder on a substrate**ABSTRACT**

For dispensing solder on a substrate (1), a soldering wire (7) and a forming gas heated to a predetermined temperature are fed to a mixing chamber (6) of a two-component nozzle (4) so that, in the mixing chamber (6), solder is melted off and carried with the gas stream. The solder blown out of the two-component nozzle (4) settles on the substrate (1). The two-component nozzle (4) is moved or swivelled relative to the substrate (1) in order to distribute the solder over a predetermined area of the substrate (1).

(Fig. 1)



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